

[File no.- 27(14)/2013-IPHW]
Government of India
Ministry of Communication & Information Technology
Department of Electronics & Information Technology (DeitY)

Date : 26 - 08-2013


ORDER

Subject: Technical Evaluation Committee (M-SIPS) for manufacturing/fab of Semiconductor Wafers/ Chips/ Chip Components/ Discrete/Power Semiconductors

Reference:

1. MSIPS Policy Gazette Notification No. 175 dated 27-07-2012
2. MSIPS Guidelines dated 07-10-2012
3. Order ref . File no. 27(14)/2013-IPHW dated 24-05-2013 regarding constitution of TEC for ATMP under M-SIPS
4. Guidelines for TEC ref File No. 27(28)/2013-IPHW dated 10-07-2013

The already approved Technical Evaluation Committee for technical evaluation of projects under M-SIPS for **Assembly Testing Marking and Packaging (ATMP) of Logic Microprocessor, Memory, Chip Components, Discrete Semiconductors, Power Semiconductors, LEDs, LCD Fabrication, LCD Glass Substrate**, constituted vide DeitY Order ref . File no. 27(14)/2013-IPHW dated 24-05-2013 shall also evaluate projects received under M-SIPS for manufacturing/fab of **Semiconductor Wafers/ Chips/ Chip Components/ Discrete/Power Semiconductors** etc. The terms of reference for the committee shall remain same as that mentioned in the aforesaid TEC order.


(Dr Ajay Kumar)
Joint Secretary
Tel : 24360160

To:

1. All Committee members

Copy to:

1. All Ministries/Departments of Govt. of India
2. Cabinet Secretariat
3. PMO
4. Planning Commission
5. Comptroller and Auditor General of India
6. JS & FA, DeitY
7. DeitY website